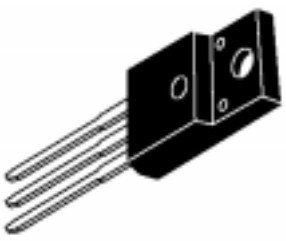
IRF830FP 4.5A 500V N CHANNEL POWER MOSFET

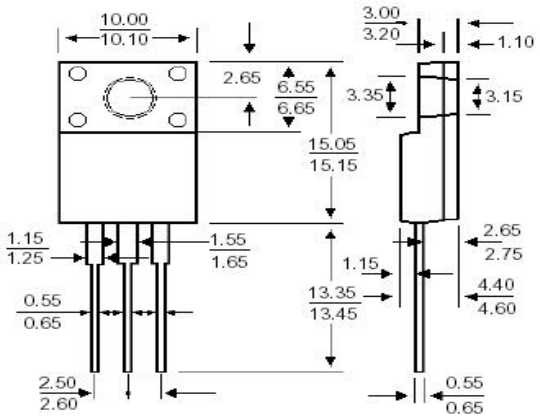
Description

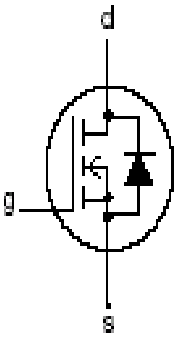
IRF830FP



ITO-220AB

Mechanical Dimensions





DIMENSION IN MM

FEATURES

- Repetitive Avalanche Rated
- Fast switching
- High thermal cycling performance
- Low thermal resistance

GENERAL DESCRIPTION

N-channel, enhancement mode field-effect power transistor, intended for use in off-line switched mode power supplies, T.V. and computer monitor power supplies, d.c. to d.c. converters, motor control circuits and general purpose switching applications.

The IRF830 is supplied in the SOT78 (TO220AB) conventional leaded package.

LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DSS}	Drain-source voltage	T_j = 25 °C to 150°C	-	500	V
V_{DGR}	Drain-gate voltage	T_j = 25 °C to 150°C; R_{GS} = 20 kΩ	-	500	V
V_{GS}	Gate-source voltage		-	± 30	V
I_D	Continuous drain current	T_{mb} = 25 °C; V_{GS} = 10 V	-	5.9	A
		T_{mb} = 100 °C; V_{GS} = 10 V	-	3.7	A
I_{DM}	Pulsed drain current	T_{mb} = 25 °C	-	24	A
P_D	Total dissipation	T_{mb} = 25 °C	-	125	W
T_j, T_{stg}	Operating junction and storage temperature range		- 55	150	°C

AVALANCHE ENERGY LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
E_{AS}	Non-repetitive avalanche energy	Unclamped inductive load, I_{AS} = 4.2 A; t_p = 0.21 ms; T_j prior to avalanche = 25°C; $V_{DD} \leq$ 50 V; R_{GS} = 50 Ω; V_{GS} = 10 V; refer to fig:17	-	287	mJ
E_{AR}	Repetitive avalanche energy[1]	I_{AR} = 5.9 A; t_p = 2.5 µs; T_j prior to avalanche = 25°C; R_{GS} = 50 Ω; V_{GS} = 10 V; refer to fig:18	-	10	mJ
I_{AS}, I_{AR}	Repetitive and non-repetitive avalanche current		-	5.9	A

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}mb}$	Thermal resistance junction to mounting base		-	-	1	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	in free air	-	60	-	K/W

ELECTRICAL CHARACTERISTICS

T_j = 25 ˚C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V; I_D = 0.25 mA	500	-	-	V
$\Delta V_{(BR)DSS}$ / ΔT_j	Drain-source breakdown voltage temperature coefficient	V_{DS} = V_{GS}; I_D = 0.25 mA	-	0.1	-	%/K
$R_{DS(ON)}$	Drain-source on resistance	V_{GS} = 10 V; I_D = 3 A	-	1.2	1.5	Ω
$V_{GS(TO)}$	Gate threshold voltage	V_{DS} = V_{GS}; I_D = 0.25 mA	2.0	3.0	4.0	V
g_{fs}	Forward transconductance	V_{DS} = 30 V; I_D = 3 A	2	3.6	-	S
I_{DSS}	Drain-source leakage current	V_{DS} = 500 V; V_{GS} = 0 V	-	1	25	µA
		V_{DS} = 400 V; V_{GS} = 0 V; T_j = 125 ˚C	-	30	250	µA
I_{GSS}	Gate-source leakage current	V_{GS} = ±30 V; V_{DS} = 0 V	-	10	200	nA
$Q_{g(tot)}$	Total gate charge	I_D = 6 A; V_{DD} = 400 V; V_{GS} = 10 V	-	53	64	nC
Q_{gs}	Gate-source charge		-	4	6	nC
Q_{gd}	Gate-drain (Miller) charge		-	28	34	nC
$t_{d(on)}$	Turn-on delay time	V_{DD} = 250 V; R_D = 39 Ω;	-	10	-	ns
t_r	Turn-on rise time	R_G = 12 Ω	-	33	-	ns
$t_{d(off)}$	Turn-off delay time		-	92	-	ns
t_f	Turn-off fall time		-	40	-	ns
L_d	Internal drain inductance	Measured from tab to centre of die	-	3.5	-	nH
L_d	Internal drain inductance	Measured from drain lead to centre of die	-	4.5	-	nH
L_s	Internal source inductance	Measured from source lead to source bond pad	-	7.5	-	nH
C_{iss}	Input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz	-	610	-	pF
C_{oss}	Output capacitance		-	96	-	pF
C_{rss}	Feedback capacitance		-	54	-	pF

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

T_j = 25 ˚C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_S	Continuous source current (body diode)	T_{mb} = 25˚C	-	-	5.9	A
I_{SM}	Pulsed source current (body diode)	T_{mb} = 25˚C	-	-	24	A
V_{SD}	Diode forward voltage	I_S = 6 A; V_{GS} = 0 V	-	-	1.2	V
t_{rr}	Reverse recovery time	I_S = 6 A; V_{GS} = 0 V; dI/dt = 100 A/µs	-	390	-	ns
Q_{rr}	Reverse recovery charge		-	4	-	µC

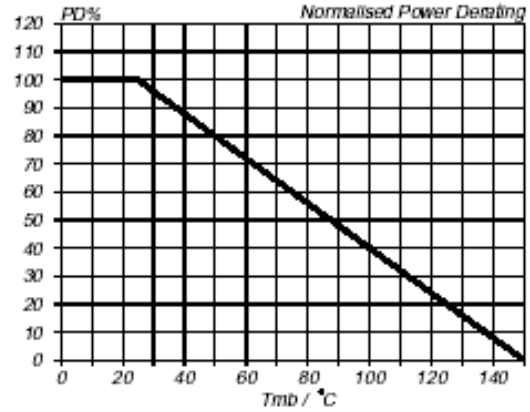


Fig.1. Normalised power dissipation.
$PD\% = 100 \cdot P_D / P_{D\,25\,°C} = f(T_{mb})$

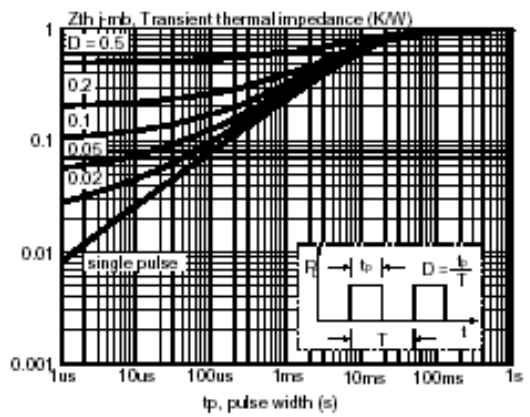


Fig.4. Transient thermal impedance.
$Z_{th\,j\text{-}mb} = f(t)$; parameter $D = t_p/T$

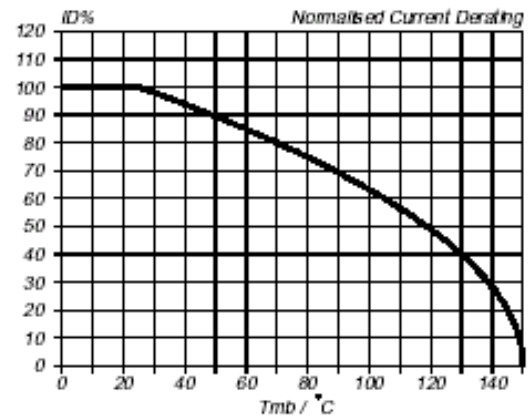


Fig.2. Normalised continuous drain current.
$ID\% = 100 \cdot I_D / I_{D\,25\,°C} = f(T_{mb})$; conditions: $V_{GS} \geq 10$ V

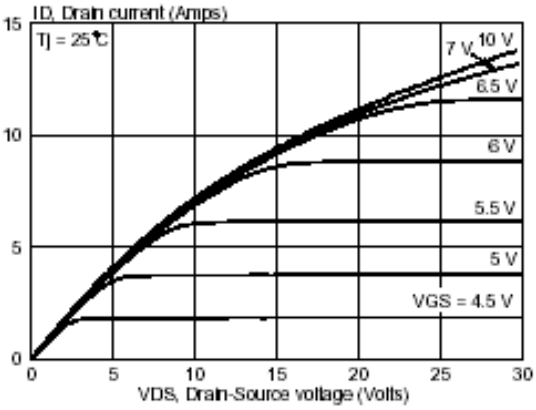


Fig.5. Typical output characteristics.
$I_D = f(V_{DS})$; parameter V_{GS}

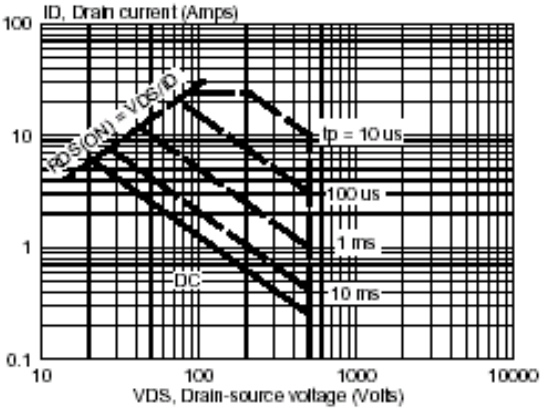


Fig.3. Safe operating area. $T_{mb} = 25$ ˚C
I_D & $I_{DM} = f(V_{DS})$; I_{DM} single pulse; parameter t_p

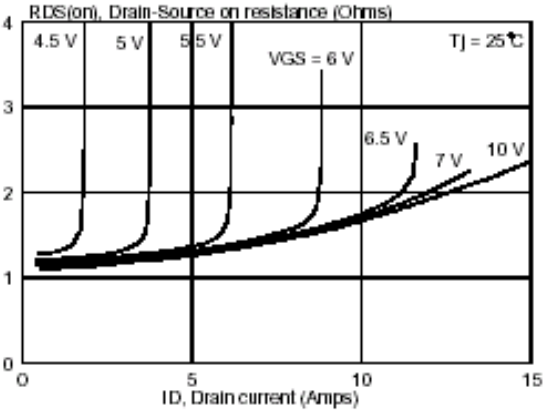


Fig.6. Typical on-state resistance.
$R_{DS(ON)} = f(I_D)$; parameter V_{GS}

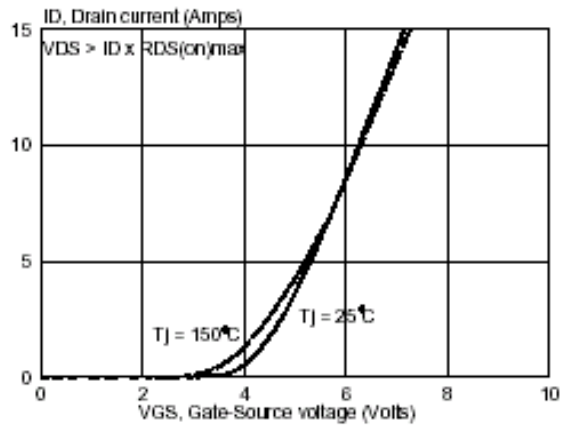


Fig.7. Typical transfer characteristics.
$I_D = f(V_{GS})$; parameter T_j

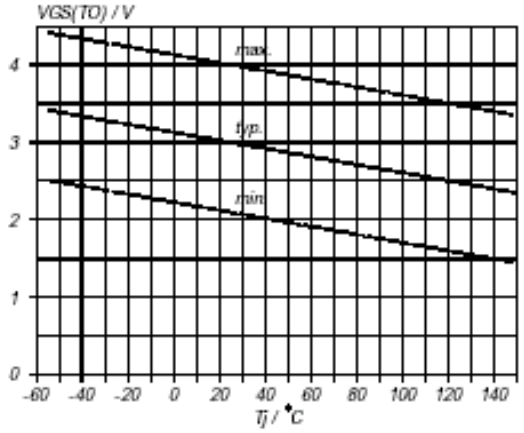


Fig.10. Gate threshold voltage.
$V_{GS(TO)} = f(T_j)$; conditions: $I_D = 0.25$ mA; $V_{DS} = V_{GS}$

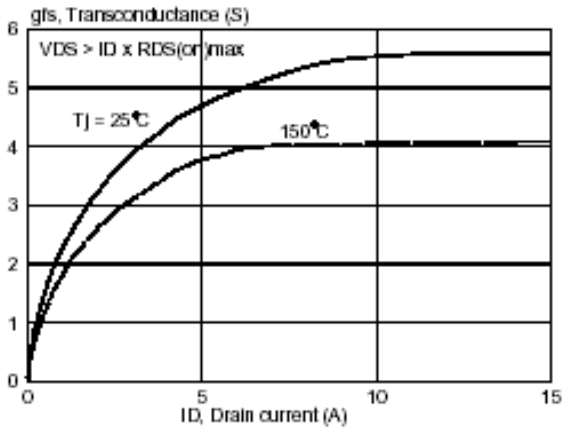


Fig.8. Typical transconductance.
$g_{fs} = f(I_D)$; parameter T_j

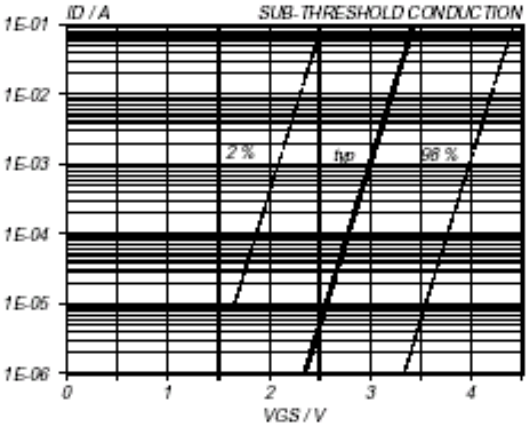


Fig.11. Sub-threshold drain current.
$I_D = f(V_{GS})$; conditions: $T_j = 25$ °C; $V_{DS} = V_{GS}$

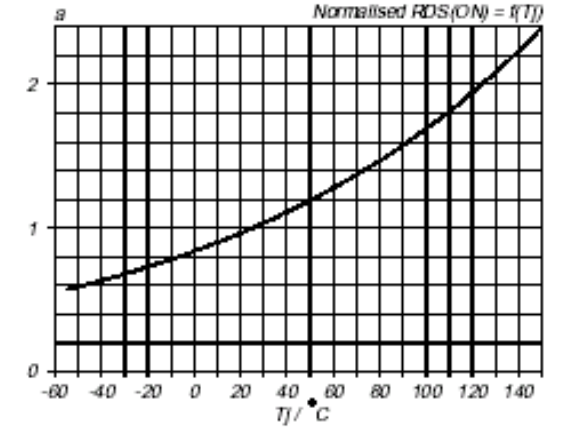


Fig.9. Normalised drain-source on-state resistance.
$a = R_{DS(ON)}/R_{DS(ON)25\,°C} = f(T_j)$; $I_D = 3$ A; $V_{GS} = 10$ V

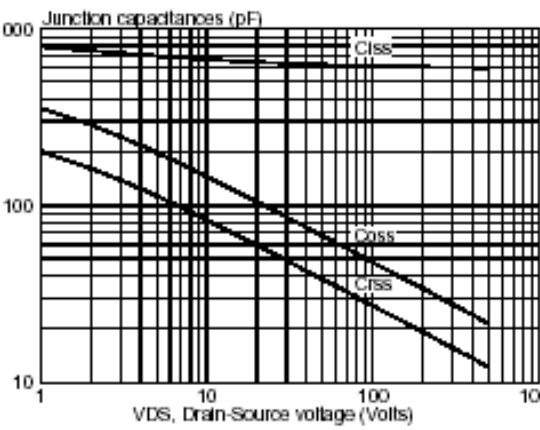


Fig.12. Typical capacitances, C_{iss}, C_{oss}, C_{rss}.
$C = f(V_{DS})$; conditions: $V_{GS} = 0$ V; $f = 1$ MHz

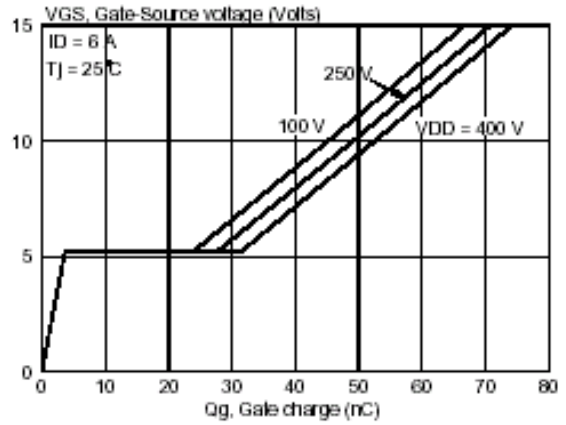


Fig.13. Typical turn-on gate-charge characteristics. $V_{GS} = f(Q_G)$; parameter V_{DS}

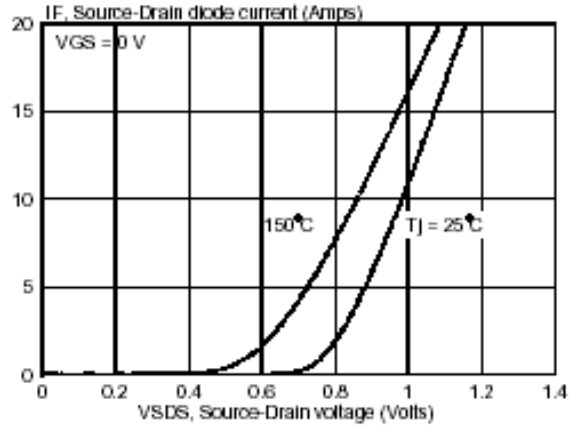


Fig.16. Source-Drain diode characteristic. $I_F = f(V_{SDS})$; parameter T_j

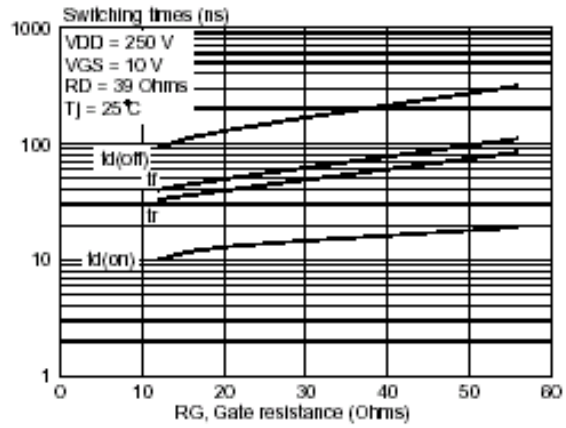


Fig.14. Typical switching times; $t_{d(on)}$, t_r, $t_{d(off)}$, $t_f = f(R_G)$

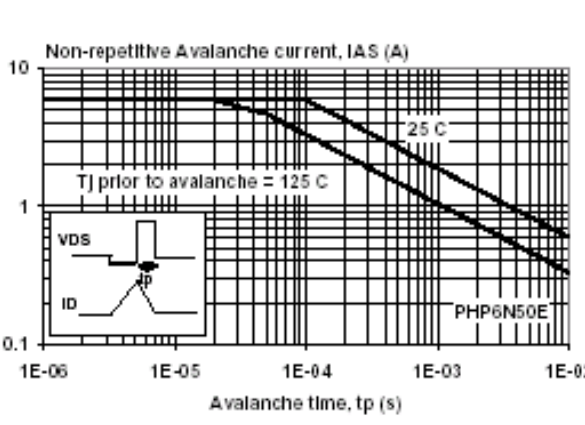


Fig.17. Maximum permissible non-repetitive avalanche current (I_{AS}) versus avalanche time (t_p); unclamped inductive load

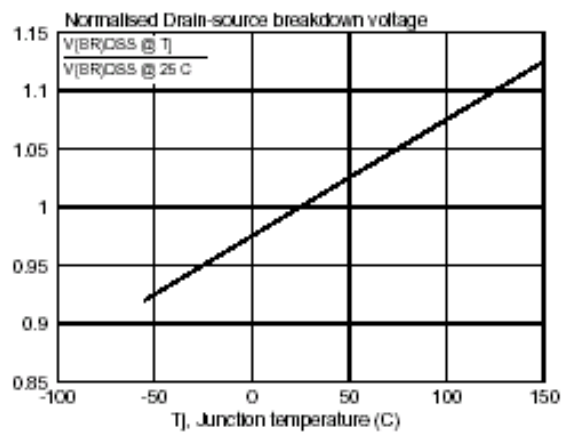


Fig.15. Normalised drain-source breakdown voltage; $V_{(BR)DSS}/V_{(BR)DSS\ 25\ °C} = f(T_j)$

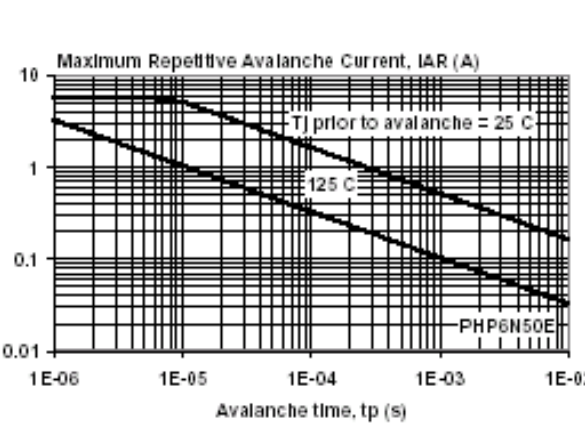


Fig.18. Maximum permissible repetitive avalanche current (I_{AR}) versus avalanche time (t_p)